



Title of Change:	Update Notification for PB21550X - Conversion of SMC packaged devices to the 403AC case outline.
Proposed first ship date:	9 March 2017
Contact information:	Contact your local ON Semiconductor Sales Office or <SitiNurhaza.MohdRamli@onsemi.com> or <SengMun.Yoon@onsemi.com>
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <SitiNurhaza.MohdRamli@onsemi.com>
Type of notification:	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____

Change Sub-Category(s): <input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change		<input checked="" type="checkbox"/> Datasheet/Product Doc change <input checked="" type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____
--	--	---

Sites Affected:			
<input type="checkbox"/> All site(s)	<input type="checkbox"/> not applicable	<input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Seremban, Malaysia	<input type="checkbox"/> External Foundry/Subcon site(s)

Description and Purpose:

This Update Notification announces that the case outline of SMC packaged devices will migrate from 403-03 to 403AC. Case outline 403AC includes the change from the legacy polarity notch to the industry standard polarity band and incorporates minor dimensional changes. The dimensional changes provide clarification of lead forming details and will allow ON Semiconductor to ultimately migrate products obtained from the recent Fairchild acquisition to a single common case outline.

PB21550X was previously released to announce that ON Semiconductor Malaysia is converting the diode polarity identification for SMC packaged devices from a notch molded into the epoxy body of the device to a laser marked polarity band.

The change will align ON Semiconductor Malaysia with the current industry standard for SMC polarity identification. The details of this change are displayed pictorially in Figure 1 below. An example device showing both the legacy notch that will be eliminated and the polarity band that will be replacing it is shown in Figure 2.

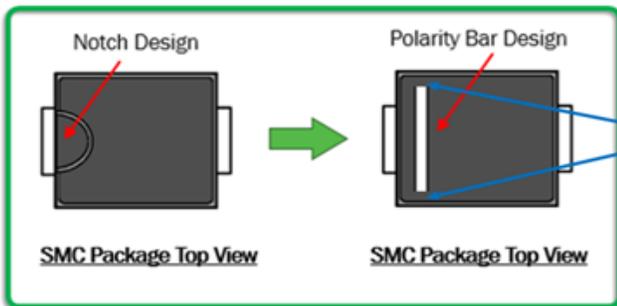


Figure 1



Figure 2

**List of affected Standard Parts:**

MBRS3100T3G	MBRS360T3G	MURS320T3G	NRVBS3100T3G	SBRS8320T3G
MBRS3100T3H	MBRS360T3H	MURS320T3H	NRVBS3201T3G	SBRS8340T3G
MBRS3201T3G	MBRS410ET3G	MURS340T3G	NRVBS330T3G	SURS8320T3G
MBRS320T3G	MBRS410LT3G	MURS360T3G	NRVBS360T3G	SURS8340T3G
MBRS330T3G	MBRS4201T3G	MURS360T3H	NRVBS410LT3G	SURS8360T3G
MBRS340T3G	MBRS540T3G	MURS480ET3G	NRVBS4201T3G	
MBRS340T3H	NSV50350AST3G	NSI50350AST3G	NRVBS540T3G	

List of affected Customer Specific Parts:

NOTE: Please be informed that parts impacted by this PDN/PCN are Special/Customer specific parts, thus MPN & CPN info will be available to affected customers only by clicking the ["Custom PCN for Selected Company Button"](#) in the Document Analysis page of PCMS/PCN Alert.